MODEL: HSS-B20-NP-01 | DESCRIPTION: HEAT SINK

FEATURES

- TO-220 package
- round hole for component attachment
- low profile design
- black anodized finish

RoHS

MODEL

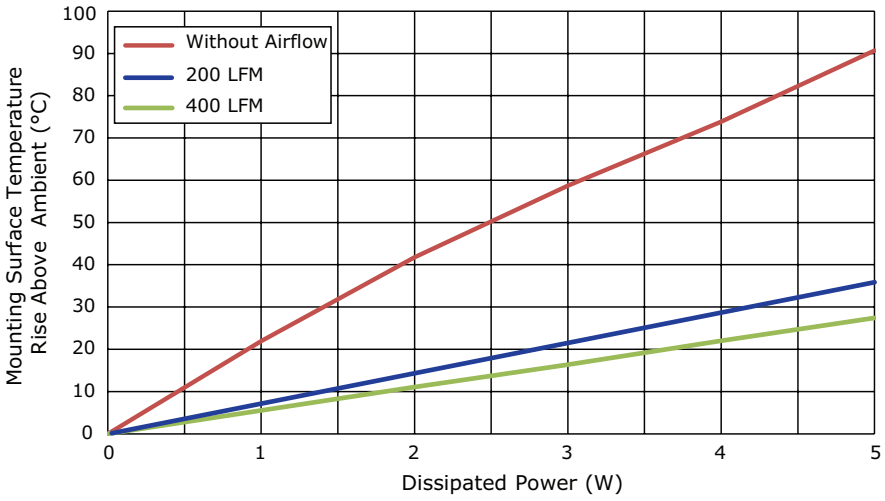
MODEL	thermal resistance[1]				power dissipation[1]
	@ 75°C ΔT, nat conv (°C/W)	@ 1 W, nat conv (°C/W)	@ 1 W, 200 LFM (°C/W)	@ 1 W, 400 LFM (°C/W)	@ 75°C ΔT, nat conv (W)
HSS-B20-NP-01	18.29	21.92	7.05	5.56	4.10

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

	Heatsink Temperature Rise Above Ambient (ΔT = Ths - Ta) (°C)		
Power (W)	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	21.92	7.05	5.56
2	41.78	14.01	11.07
3	58.69	21.06	16.38
4	73.87	28.48	22.02
5	90.68	35.84	27.40

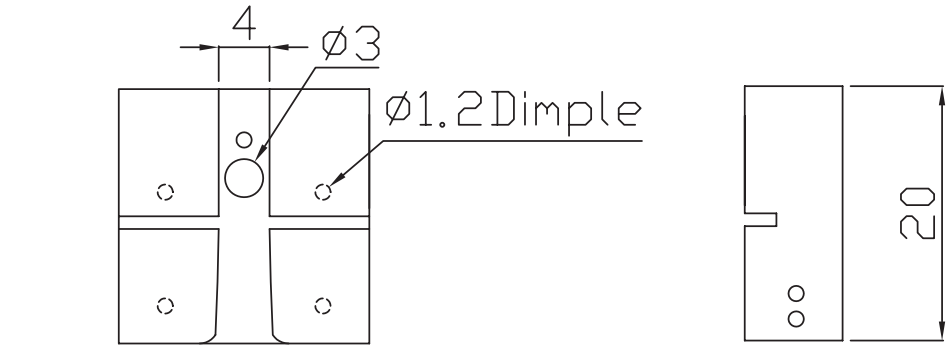
Ths: "hot spot" temperature measured on the heatsink
Ta: ambient temperature

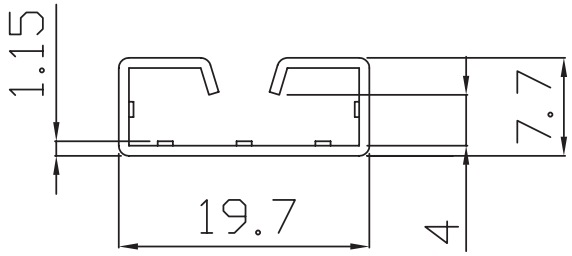


MECHANICAL DRAWING

units: mm
tolerance: ±0.5 mm

MATERIAL	AL5052
FINISH	black anodized
THICKNESS	0.8 mm
WEIGHT	2.4 g





REVISION HISTORY

rev.	description	date
1.0	initial release	03/29/2017
1.01	brand update	02/13/2020
1.02	logo, datasheet style update	08/05/2022
1.03	CUI Devices rebranded to Same Sky	09/12/2024

The revision history provided is for informational purposes only and is believed to be accurate.